# **Surface Mount Schottky Power Rectifier**

# Plastic SOD-123 Package

metal-to-silicon power diode. Ideally suited for low voltage, high frequency rectification or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system. This package also provides an easy to work with alternative to leadless 34 package style. Because of its small size, it is ideal for use in portable and battery powered products such as cellular and cordless phones, chargers, notebook computers, printers, PDAs and PCMCIA cards. Typical applications are ac/dc and dc-dc converters, reverse battery protection, and "Oring" of multiple supply voltages and any other application where performance and size are critical. These state-of-the-art devices have the following features:

- Guardring for Stress Protection
- Low Leakage
- 150°C Operating Junction Temperature
- Epoxy Meets UL94, V0 at 1/8"
- Package Designed for Optimal Automated Board Assembly
- ESD Ratings: Machine Model, C Human Body Model, 3B

#### **Mechanical Characteristics**

- Reel Options: MBR120ESFT1 = 3,000 per 7" reel/8 mm tape MBR120ESFT3 = 10,000 per 13" reel/8 mm tape
- Device Marking: L2E
- Polarity Designator: Cathode Band
- Weight: 11.7 mg (approximately)
- Case: Epoxy, Molded
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds



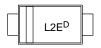
http://onsemi.com

SCHOTTKY BARRIER
RECTIFIER
1.0 AMPERES
20 VOLTS



SOD-123FL CASE 498 PLASTIC

#### **DEVICE MARKING**



L2E = Specific Device Code D = Date Code

#### ORDERING INFORMATION

Device	Package	Shipping
MBR120ESFT1	SOD-123FL	3000/Tape & Reel
MBR120ESFT3	SOD-123FL	10,000/Tape & Reel

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	20	V
Average Rectified Forward Current (At Rated V <sub>R</sub> , T <sub>L</sub> = 140°C)	Io	1.0	А
Peak Repetitive Forward Current (At Rated V <sub>R</sub> , Square Wave, 20 kHz, T <sub>L</sub> = 125°C)	I <sub>FRM</sub>	2.0	A
Non-Repetitive Peak Surge Current (Non-Repetitive peak surge current, halfwave, single phase, 60 Hz)	I <sub>FSM</sub>	40	A
Storage Temperature	T <sub>stg</sub>	-65 to 150	°C
Operating Junction Temperature	TJ	-65 to 150	°C
Voltage Rate of Change (Rated V <sub>R</sub> , T <sub>J</sub> = 25°C)	dv/dt	10,000	V/μs

#### THERMAL CHARACTERISTICS

Thermal Resistance – Junction–to–Lead (Note 1)	R <sub>til</sub>	26	°C/W	
Thermal Resistance – Junction–to–Lead (Note 2)	R <sub>til</sub>	21		
Thermal Resistance – Junction–to–Ambient (Note 1)	$R_{tja}$	325		
Thermal Resistance – Junction–to–Ambient (Note 2)	R <sub>tja</sub>	82		

- 1. Mounted with minimum recommended pad size, PC Board FR4.
- 2. Mounted with 1 in. copper pad (Cu area 700 mm<sup>2</sup>).

#### **ELECTRICAL CHARACTERISTICS**

Maximum Instantaneous Forward Voltage (Note 3), See Figure 2	V <sub>F</sub>	$T_J = 25^{\circ}C$	T <sub>J</sub> = 100°C	٧
$(I_F = 0.1 \text{ A})$ $(I_F = 1.0 \text{ A})$ $(I_F = 2.0 \text{ A})$		0.455 0.530 0.595	0.360 0.455 0.540	
Maximum Instantaneous Reverse Current (Note 3), See Figure 4	I <sub>R</sub>	T <sub>1</sub> = 25°C	T <sub>1</sub> = 100°C	μA
3	- K	. J = = 0 0	. 5	pu t

<sup>3.</sup> Pulse Test: Pulse Width  $\leq$  250  $\mu$ s, Duty Cycle  $\leq$  2%.

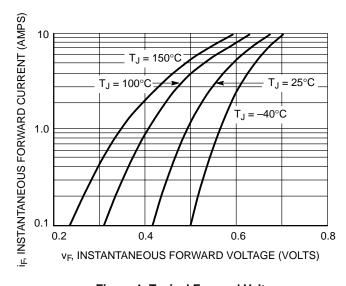


Figure 1. Typical Forward Voltage

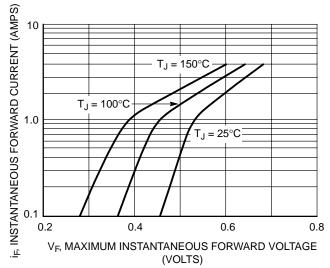
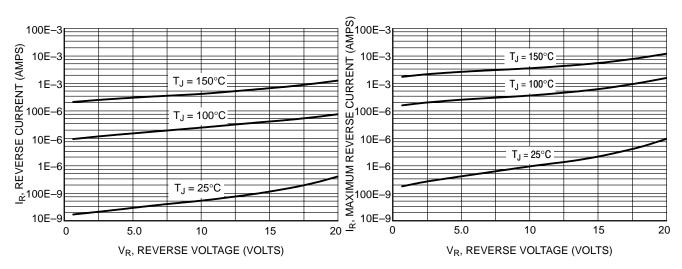


Figure 2. Maximum Forward Voltage



**Figure 3. Typical Reverse Current** 

**Figure 4. Maximum Reverse Current** 

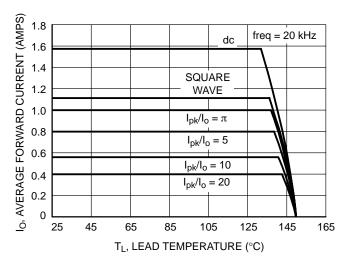


Figure 5. Current Derating

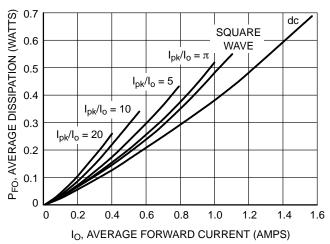


Figure 6. Forward Power Dissipation

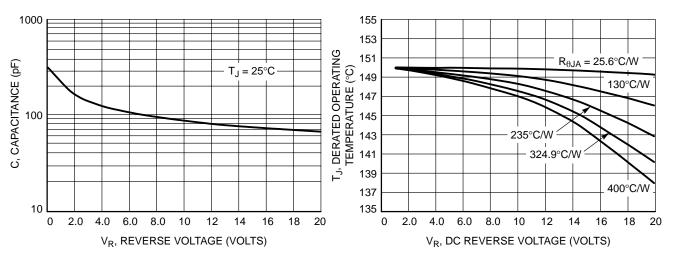


Figure 7. Capacitance

Figure 8. Typical Operating Temperature Derating\*

\* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of  $T_J$  therefore must include forward and reverse power effects. The allowable operating  $T_J$  may be calculated from the equation:  $T_J = T_{Jmax} - r(t)(Pf + Pr)$  where

r(t) = thermal impedance under given conditions,

Pf = forward power dissipation, and

Pr = reverse power dissipation

This graph displays the derated allowable  $T_J$  due to reverse bias under DC conditions only and is calculated as  $T_J = T_{Jmax} - r(t)Pr$ , where r(t) = Rthja. For other power applications further calculations must be performed.

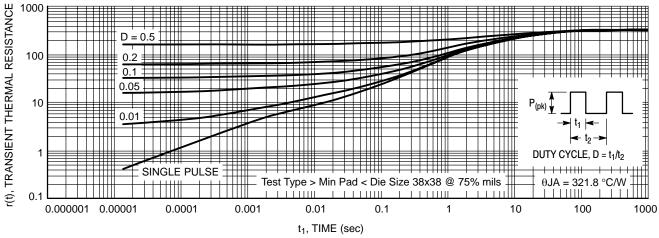
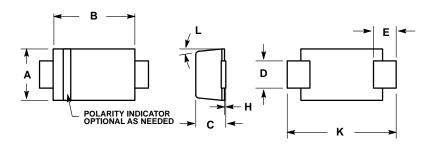
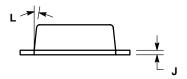


Figure 9. Thermal Response

#### **PACKAGE DIMENSIONS**

SOD-123LF CASE 498-01 ISSUE O

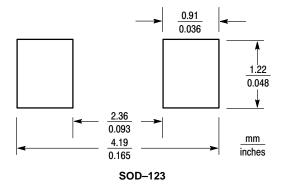




- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH.
  4. DIMENSIONS D AND J ARE TO BE MEASURED ON FLAT SECTION OF THE LEAD: BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	1.50	1.80	0.059	0.071	
В	2.50	2.90	0.098	0.114	
C	0.90	1.00	0.035	0.039	
D	0.70	1.10	0.028	0.043	
Е	0.55	0.95	0.022	0.037	
Н	0.00	0.10	0.000	0.004	
ſ	0.10	0.20	0.004	0.008	
K	3.40	3.80	0.134	0.150	
٦	0°	8 °	0 °	8 °	

# **RECOMMENDED FOOTPRINT FOR SOD-123FL**





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